

# FCR120N40M2A

## N-Channel eSiC Silicon Carbide Power MOSFET

1200 V, 57 A, 40 mΩ



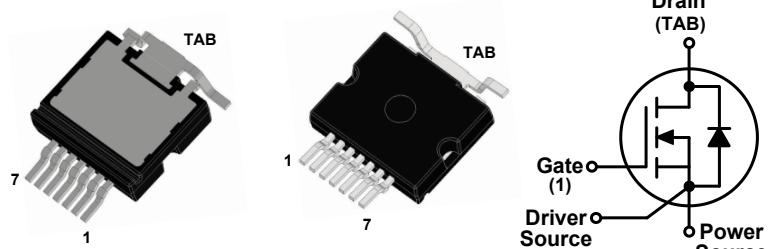
### Features

- High switching speed with a low gate charge
- Fast intrinsic diode with low reverse recovery
- Robust Avalanche Capability
- 100% Avalanche Tested
- Pb-free, Halogen Free, and RoHS Compliant
- AEC Q101 Qualified

BV <sub>DSS</sub> , T <sub>c</sub> =25°C	I <sub>D</sub> , T <sub>c</sub> =25°C	R <sub>DS(on),typ</sub>	Q <sub>g,typ</sub>
1200 V	57 A	40 mΩ	62 nC

### Benefits

- Top-side-cooling package
- Kelvin source connection
- High current capability
- Higher frequency applicability
- Reduced cooling effort



### Applications

- Automotive applications (OBC, e-Comp, DC/DC)
- Solar inverter
- EV charging station
- UPS, Industrial power supply



### Absolute Maximum Ratings (T<sub>c</sub> = 25°C unless otherwise noted)

Symbol	Parameter		Value	Unit
V <sub>DSS</sub>	Drain to Source Voltage		1200	V
V <sub>GS</sub>	Gate to Source Voltage (DC)		-10 / +22	V
V <sub>GSop</sub>	Recommended Operation Value		-5...-3 / +18	V
I <sub>D</sub>	Drain Current	Continuous (T <sub>c</sub> = 25°C)	57	A
		Continuous (T <sub>c</sub> = 100°C)	40	
I <sub>DM</sub>	Drain Current	Pulsed (Note1)	142	A
P <sub>D</sub>	Power Dissipation	(T <sub>c</sub> = 25°C)	272	W
		Derate Above 25°C	1.9	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to 175	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds		260	°C

### Thermal Characteristics

Symbol	Parameter	Value	Unit
R <sub>ejc</sub>	Thermal Resistance, Junction to Case, Max.	0.55	°C/W
R <sub>eJA</sub>	Thermal Resistance, Junction to Ambient, Max.	40	

### Package Marking and Ordering Information

Part Number	Top Marking	Package	Packing Method	Quantity
FCR120N40M2A	FCR120N40M2A	TO-263-7L V2 (LF)	Tape and Reel	700 units

**Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain to Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}, I_D = 1 \text{ mA}$	1200			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 1200 \text{ V}, V_{\text{GS}} = 0 \text{ V}$		1	100	$\mu\text{A}$
		$V_{\text{DS}} = 1200 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 175^\circ\text{C}$		10		
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}} = +22 \text{ V}, V_{\text{DS}} = 0 \text{ V}$			+100	$\text{nA}$
		$V_{\text{GS}} = -10 \text{ V}, V_{\text{DS}} = 0 \text{ V}$			-100	

**On Characteristics**

$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}} = V_{\text{DS}}, I_D = 10 \text{ mA}$ (tested after $V_{\text{GS}} = 22 \text{ V}, 1 \text{ ms pulse}$ )	2.0	3.0	4.5	V
$R_{\text{DS}(\text{on})}$	Static Drain to Source On Resistance	$V_{\text{GS}} = 18 \text{ V}, I_D = 28 \text{ A}$		40.0	54.0	$\text{m}\Omega$
		$V_{\text{GS}} = 18 \text{ V}, I_D = 28 \text{ A}, T_J = 175^\circ\text{C}$		64.0		
		$V_{\text{GS}} = 15 \text{ V}, I_D = 28 \text{ A}$		55.5		
$g_{\text{fs}}$	Transconductance	$V_{\text{DS}} = 20 \text{ V}, I_D = 28 \text{ A}$		16.9		S

**Dynamic Characteristics**

$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = 800 \text{ V}, V_{\text{GS}} = 0 \text{ V}, f = 250 \text{ kHz}$		1668		$\text{pF}$
$C_{\text{oss}}$	Output Capacitance			105		
$C_{\text{rss}}$	Reverse Capacitance			4		
$E_{\text{oss}}$	Stored Energy in Output Capacitance	$V_{\text{DS}} = 0 \text{ V to } 800 \text{ V}, V_{\text{GS}} = 0 \text{ V}$		42		$\mu\text{J}$
$C_{\text{o(er)}}$	Energy Related Output Capacitance			132		$\text{pF}$
$C_{\text{o(tr)}}$	Time Related Output Capacitance			201		
$Q_{\text{g(tot)}}$	Total Gate Charge	$V_{\text{DS}} = 800 \text{ V}, I_D = 28 \text{ A}, V_{\text{GS}} = -3 \text{ V / } 18 \text{ V, Inductive load}$		62		$\text{nC}$
$Q_{\text{gs}}$	Gate to Source Charge			20		
$Q_{\text{gd}}$	Gate to Drain "Miller" Charge			14		
$R_G$	Internal Gate Resistance	$f = 1 \text{ MHz}, V_{\text{AC}} = 30 \text{ mV}$		3.0		$\Omega$

**Switching Characteristics**

$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DS}} = 800 \text{ V}, I_D = 28 \text{ A}, V_{\text{GS}} = -3 \text{ V / } 18 \text{ V, } R_G = 6.8 \Omega, \text{ FWD : PCH120S20D1, Inductive load}$		19		$\text{ns}$
$t_r$	Turn-On Rise Time			15		
$t_{\text{d(off)}}$	Turn-Off Delay Time			35		
$t_f$	Turn-Off Fall Time			8		
$E_{\text{on}}$	Turn-on Switching Energy			158		$\mu\text{J}$
$E_{\text{off}}$	Turn-off Switching Energy			100		
$E_{\text{tot}}$	Total Switching Energy			258		

**Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Source-Drain Diode Characteristics</b>						
$I_S$	Continuous Diode Forward Current	$V_{GS} = -3 \text{ V}$			57	A
$I_{SM}$	Pulsed Diode Forward Current	$V_{GS} = -3 \text{ V}$ (Note1)			142	
$V_{SD}$	Diode Forward Voltage	$V_{GS} = -3 \text{ V}, I_{SD} = 28 \text{ A}$		4.3		V
$t_{rr}$	Reverse Recovery Time	$V_{DD} = 800 \text{ V}, I_{SD} = 28 \text{ A},$ $dI_F/dt = 3000 \text{ A}/\mu\text{s}$ , Includes $Q_{oss}$		15		ns
$Q_{rr}$	Reverse Recovery Charge			219		nC
$I_{rm}$	Peak Reverse Recovery Current			24		A

※Note 1 : Limited by maximum junction temperature.

※Note 2 : LF discoloration and Picker Circle Printing allowed.

## Typical Performance Characteristics

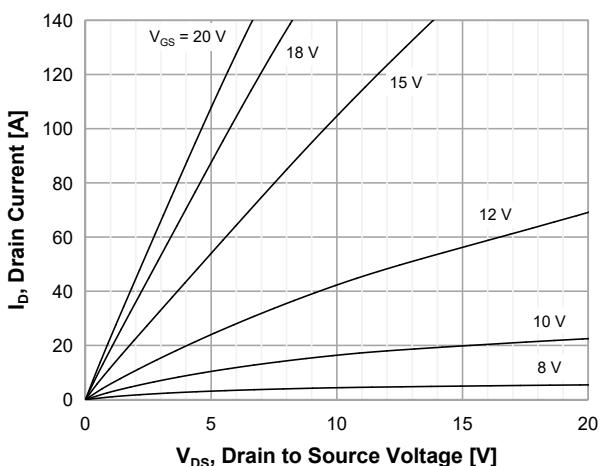
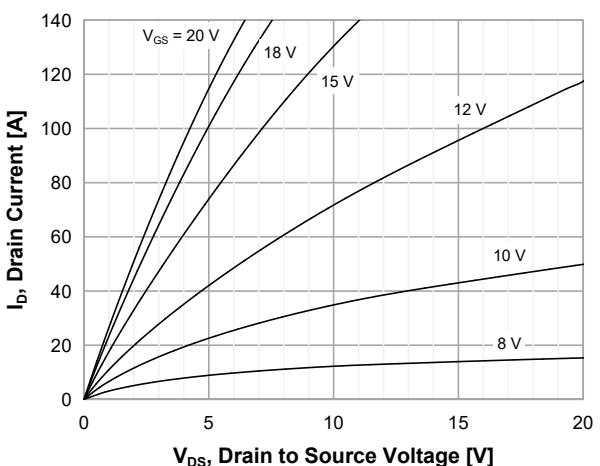
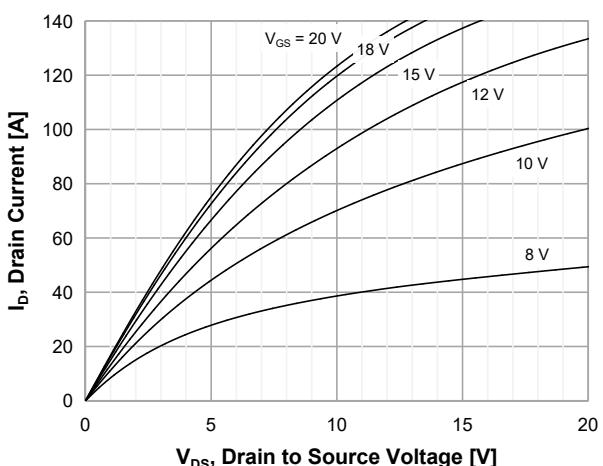
Figure 1. On-Region Characteristics  $T_J = -40^\circ\text{C}$ Figure 2. On-Region Characteristics  $T_J = 25^\circ\text{C}$ Figure 3. On-Region Characteristics  $T_J = 175^\circ\text{C}$ 

Figure 4. Normalized On-Resistance Characteristics v s. Temperature

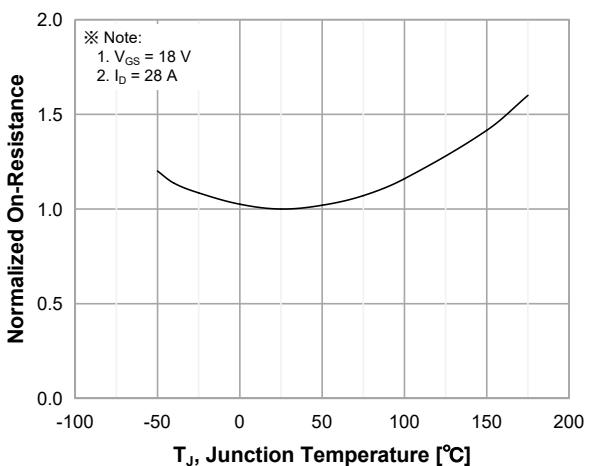
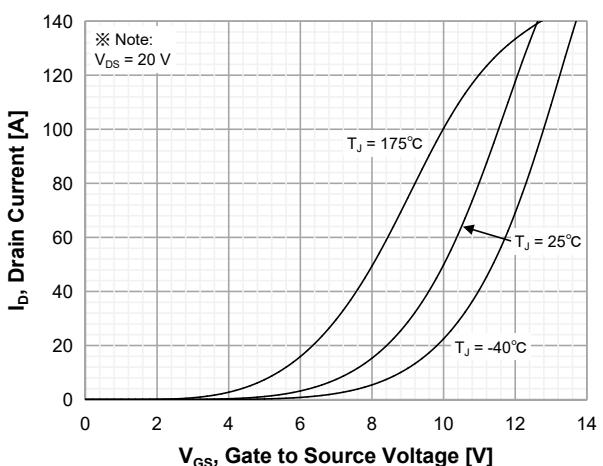
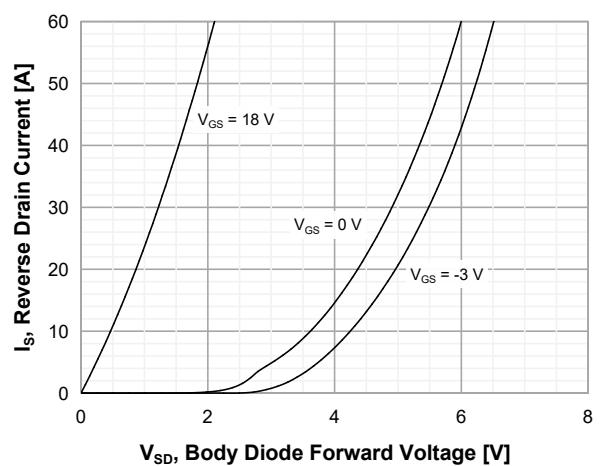
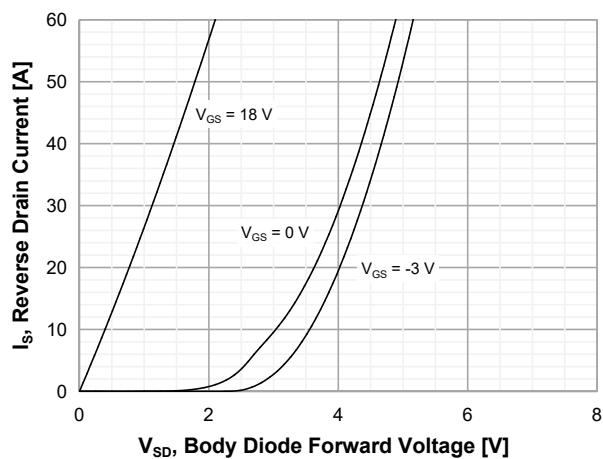


Figure 5. Transfer Characteristics

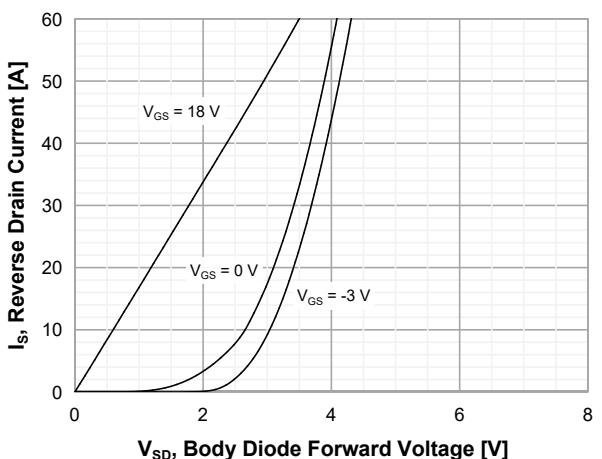
Figure 6. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = -40^\circ\text{C}$ 

### Typical Performance Characteristics

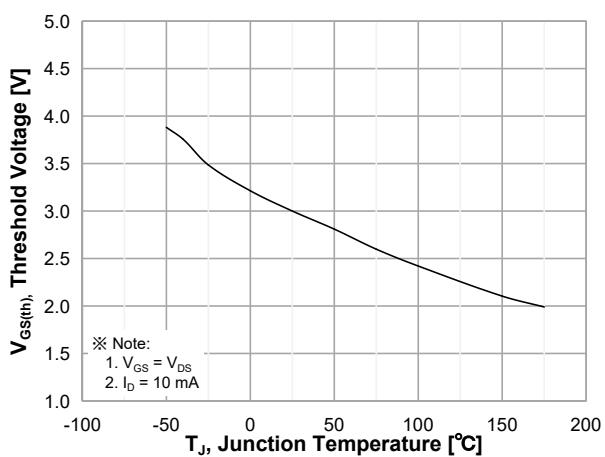
**Figure 7. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = 25^\circ\text{C}$**



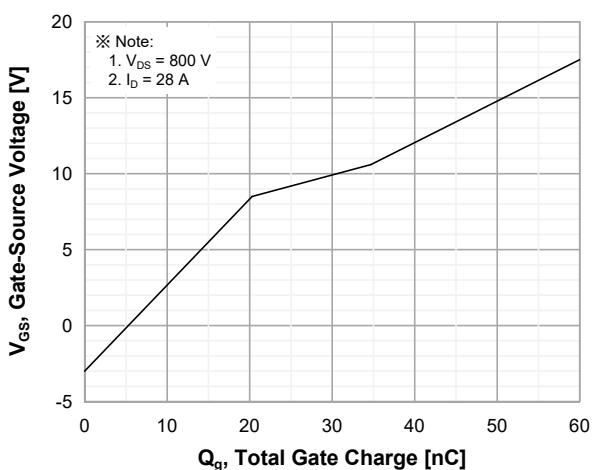
**Figure 8. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = 175^\circ\text{C}$**



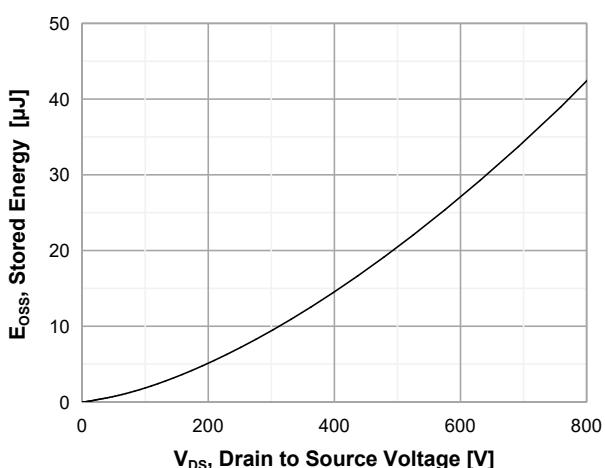
**Figure 9. Threshold Voltage vs. Temperature**



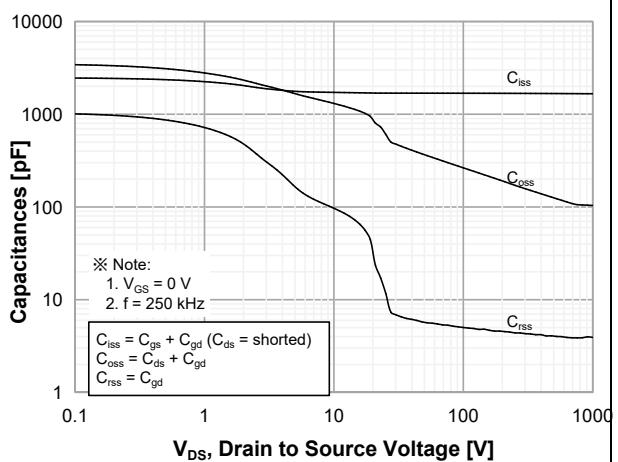
**Figure 10. Gate Charge Characteristics**



**Figure 11. Stored Energy in Output Capacitance**

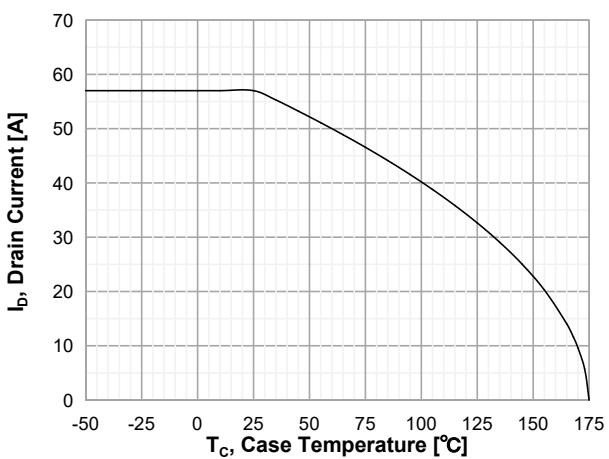


**Figure 12. Capacitance Characteristics**

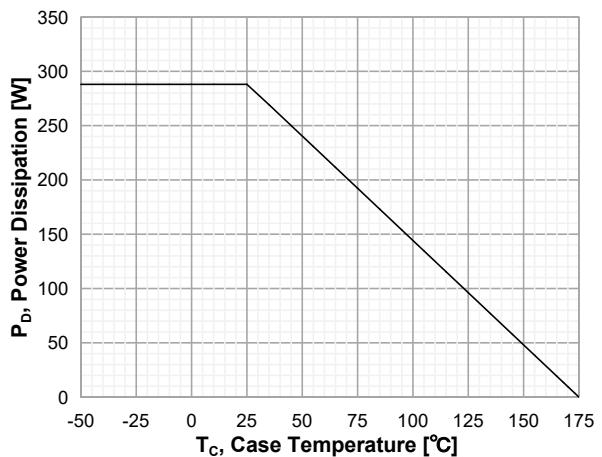


### Typical Performance Characteristics

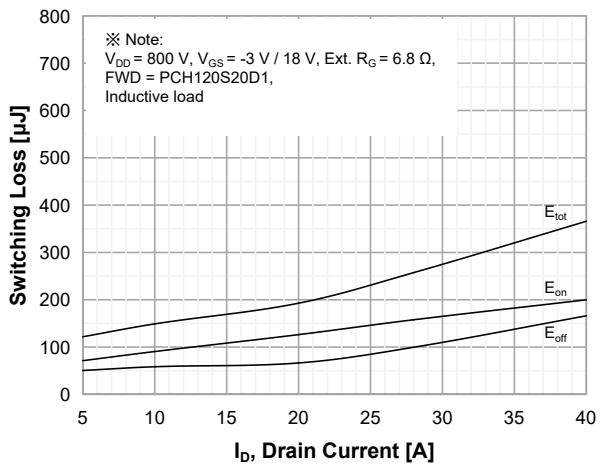
**Figure 13. Continuous Drain Current Derating vs. Case Temperature**



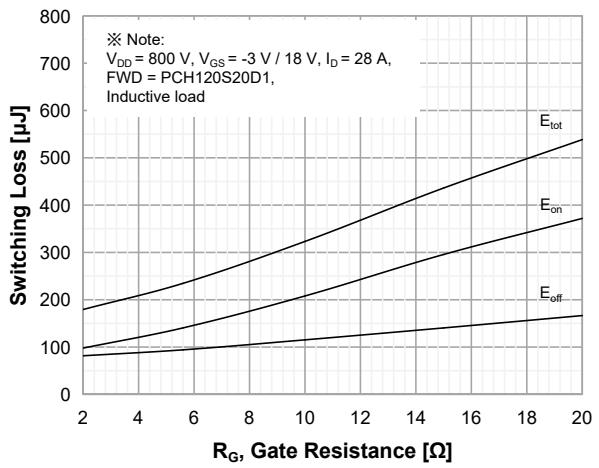
**Figure 14. Maximum Power Dissipation Derating vs. Case Temperature**



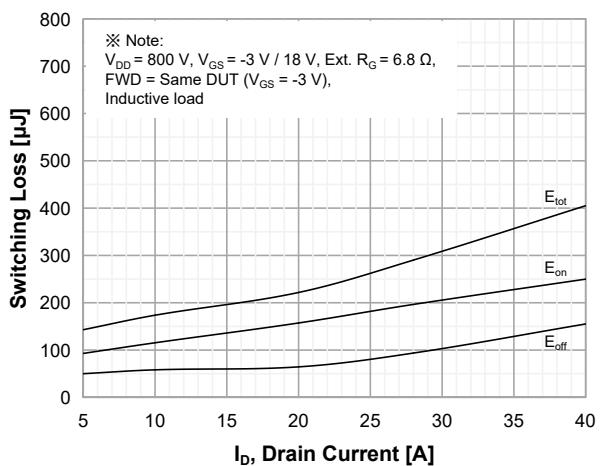
**Figure 15. Typ. Switching Losses vs. Drain Current**



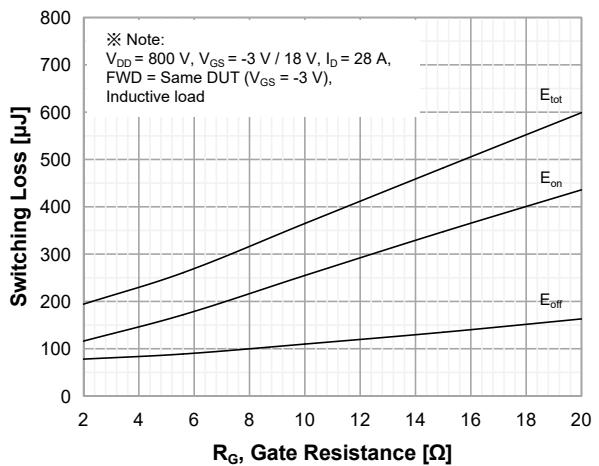
**Figure 16. Typ. Switching Losses vs. Gate Resistance**



**Figure 17. Typ. Switching Losses vs. Drain Current**



**Figure 18. Typ. Switching Losses vs. Gate Resistance**



## Typical Performance Characteristics

Figure 19. Maximum Safe Operating Area

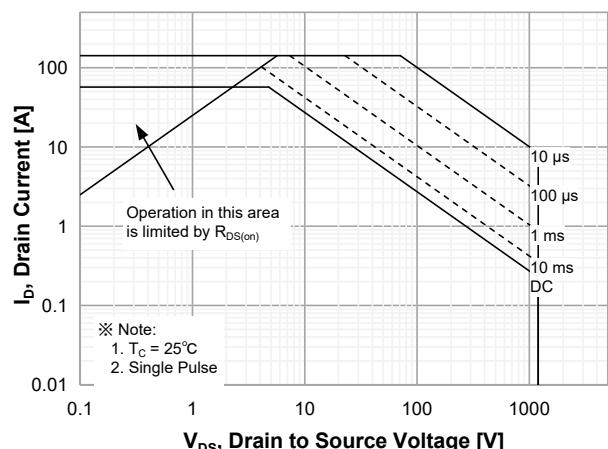


Figure 20. Transient Thermal Response Curve

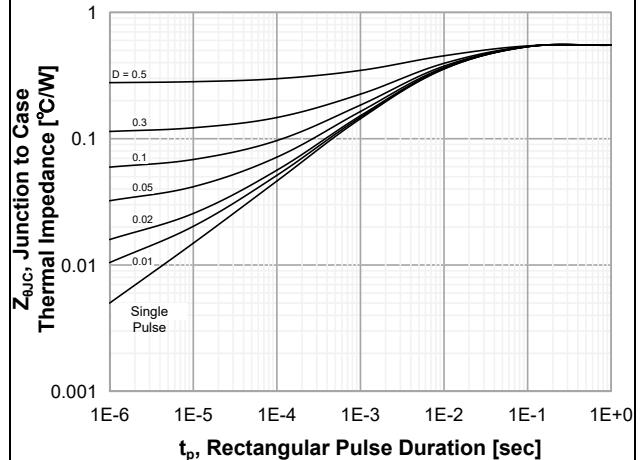


Figure 21. Inductive Load Switching Test Circuit and Waveforms

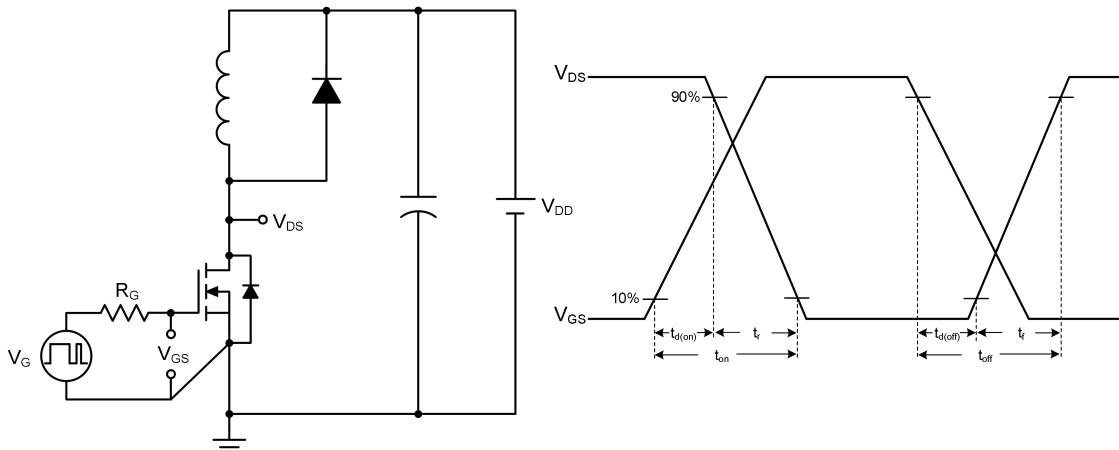
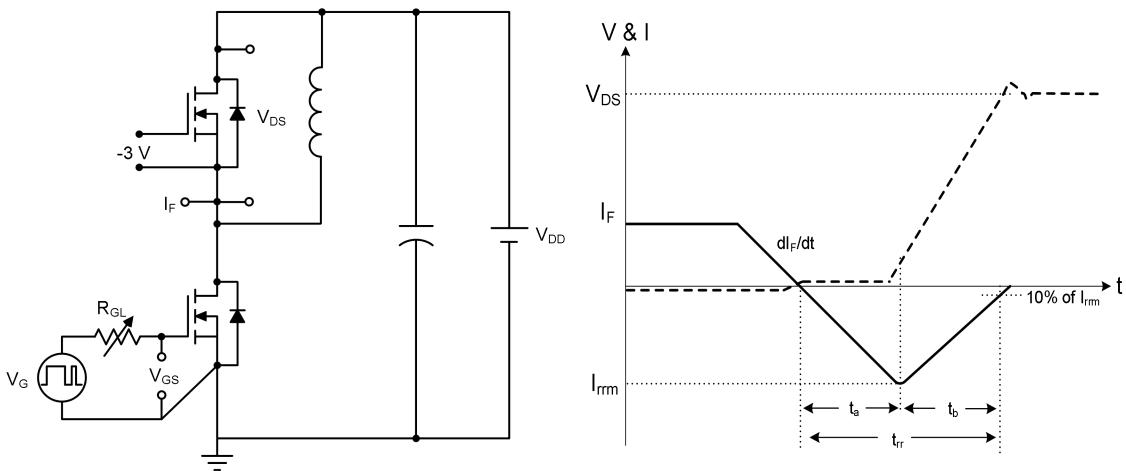
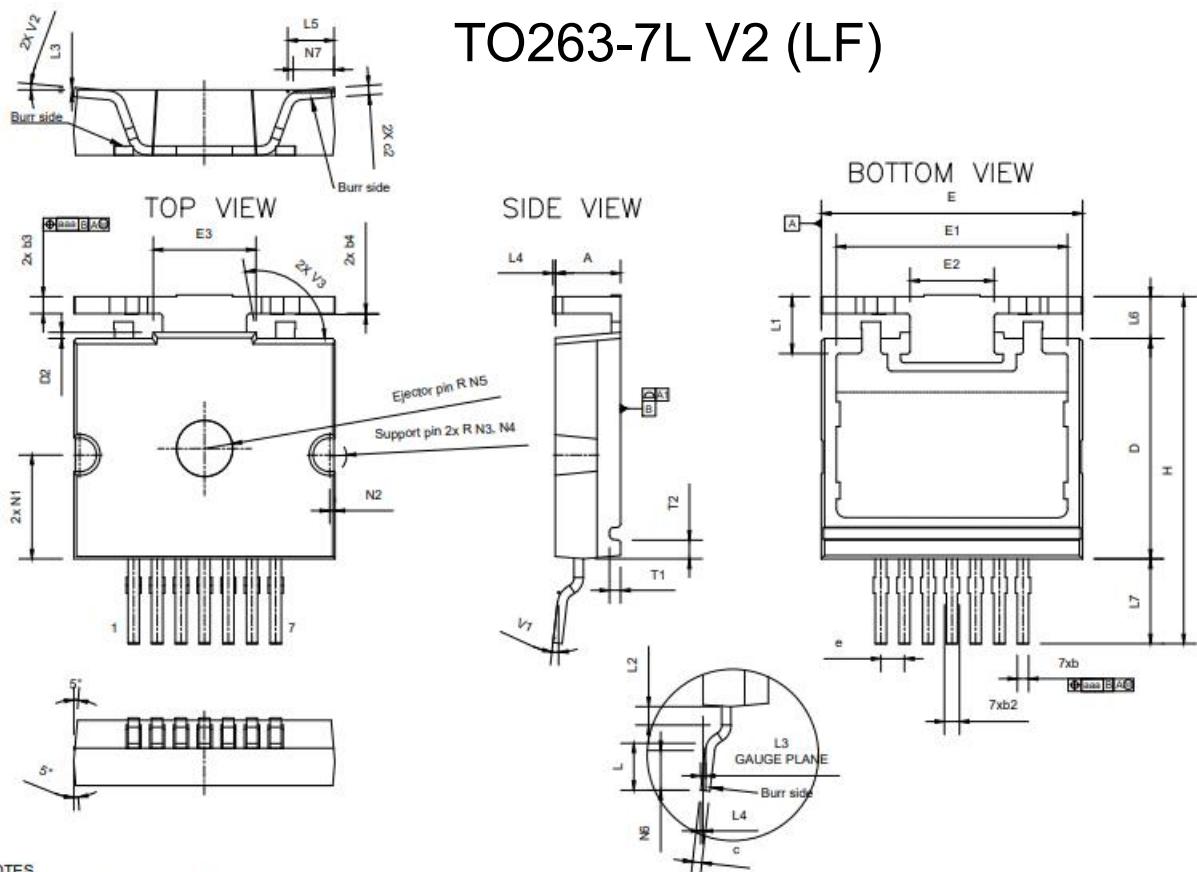


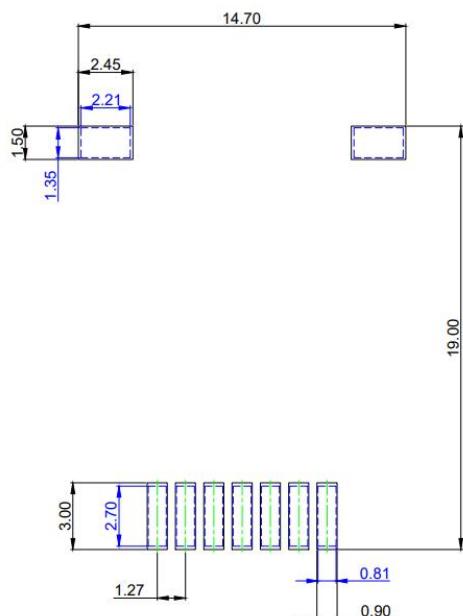
Figure 22. Peak Diode Recovery dv/dt Test Circuit and Waveforms



## Package Outlines



[ Footprint guide]



## Package Outlines

SYMBOL	Common		
	DIMENSIONS MILLIMETER		
	MIN.	NOM.	MAX.
A	3.40	3.50	3.60
A1		0.05	
b	0.50	0.60	0.70
b2	0.70	0.80	0.90
b3	0.80	0.90	0.98
b4	Ref only. 0.05mm		
c	0.40	0.50	0.60
c2	0.40	0.50	0.60
D	11.70	11.80	11.90
D1	7.78	7.88	7.98
D2	0.24	0.34	0.44
E	13.90	14.00	14.10
E1	12.30	12.40	12.50
E2	4.45	4.50	4.55
E3	5.45	5.50	5.55
e	1.27		
H	18.00	18.58	19.00
L	2.42	2.52	2.62
L1	3.04		
L2	0.90	1.00	1.10
L3	0.26		
L4	0.075	0.125	0.175
L5	2.38	2.48	2.58
L6	2.14	2.24	2.34
L7	4.44	4.54	4.64
N1	5.46	5.56	5.66
N2	0.25	0.30	0.35
N3	0.80	0.90	1.00
N4	1.00	1.10	1.20
N5	1.40	1.50	1.60
N6	2.185	2.285	2.385
N7	2.10	2.20	2.30
T1	0.60		
T2	1.00		
T3	0.60	0.70	0.80
V1	0°	5°	8°
V2	0°	6°	8°
V3	100°		
aaa	0.1		